

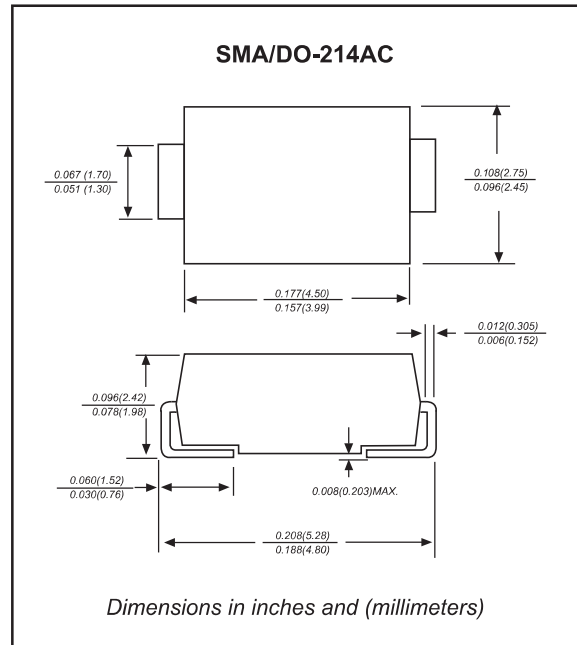
### Features

- ▶ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ▶ For surface mounted applications
- ▶ Metal silicon junction, majority carrier conduction
- ▶ Low power loss, high efficiency
- ▶ Built-in strain relief, ideal for automated placement
- ▶ High forward surge current capability
- ▶ High temperature soldering guaranteed: 250°C/10 seconds at terminals
- ▶ Compliant to RoHS Directive 2011/65/EU
- ▶ Compliant to Halogen-free
- ▶ Suffix "-Q1" for AEC-Q101

### Mechanical data

- ▶ **Case:** JEDEC DO-214AC molded plastic body
- ▶ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ▶ **Polarity:** Color band denotes cathode end
- ▶ **Mounting Position:** Any

### Package outline



### Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	$I_O$			1.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	$I_{FSM}$			30	A
Reverse current	$V_R = V_{RRM} \quad T_A = 25^\circ\text{C}$	$I_R$			0.5	mA
	$V_R = V_{RRM} \quad T_A = 100^\circ\text{C}$				10	
Thermal resistance	Junction to ambient NOTE 1	$R_{\theta JA}$		88		$^\circ\text{C}/\text{W}$
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	$C_J$		110		pF
Storage temperature		$T_{STG}$	-65		+150	$^\circ\text{C}$

**Note:** 1.P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas

SYMBOLS	$V_{RM}^{*1}$ (V)	$V_{RMS}^{*2}$ (V)	$V_R^{*3}$ (V)	$V_F^{*4}$ (V)	Operating temperature $T_J$ , ( $^\circ\text{C}$ )
SU14-A-Q1	40	28	40	0.40	-55 to +125

\*1 Repetitive peak reverse voltage

\*2 RMS voltage

\*3 Continuous reverse voltage

\*4 Maximum forward voltage@ $I_F=1.0\text{A}$

### Rating and characteristic curves

Fig. 1 Forward Current Derating Curve

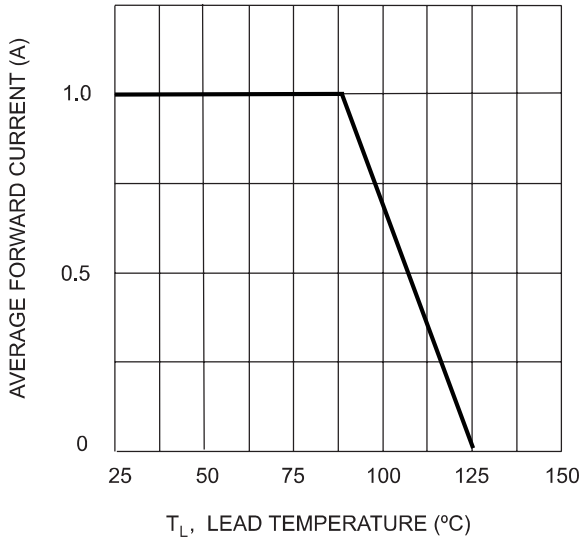


Fig. 2 Typ. Forward Characteristics

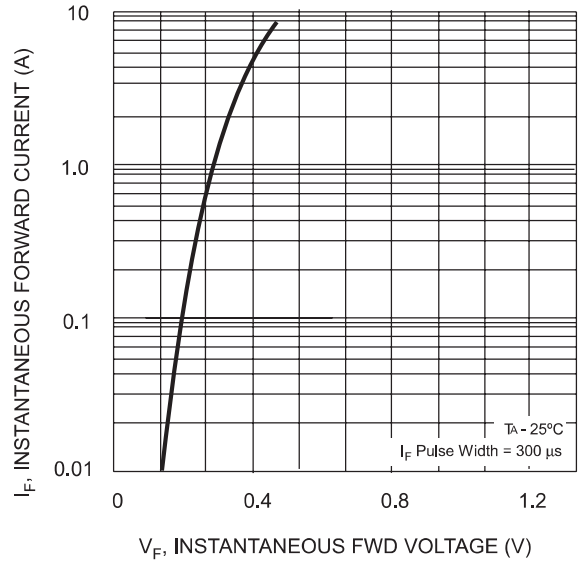


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

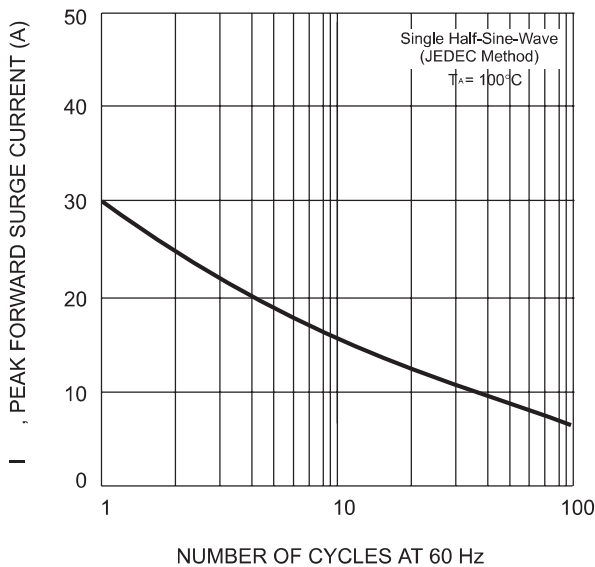
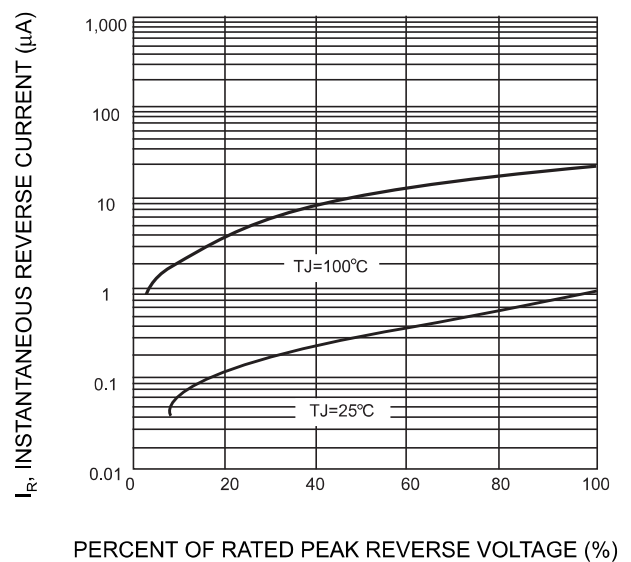




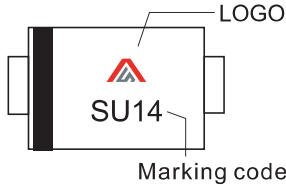
Fig. 4 Typical Reverse Characteristics (per element)



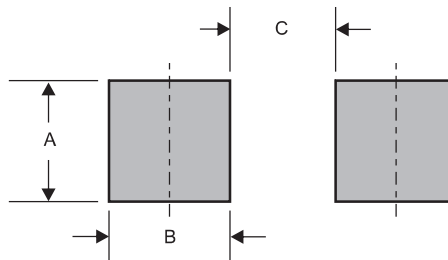
### Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

### Marking

Type number	Marking code	Example
SU14-A-Q1	SU14	

### Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMA	0.110 (2.80)	0.063 (1.60)	0.087 (2.20)